

For immediate release

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## **NEXX Systems Celebrates Shipment of 100<sup>th</sup> Deposition System**

**Hsinchu, Taiwan and Billerica, MA – November 19, 2009** – NEXX Systems, a leading provider of processing equipment for advanced wafer-level packaging applications, yesterday celebrated the shipment of its 100<sup>th</sup> deposition system. The system, a Stratus S300 electrodeposition tool, is being installed at a major Taiwan OSAT (outsourced assembly and test) fab.

In a celebration held Wednesday in Hsinchu, Oliver Hung, General Manager of NEXX Systems Taiwan, remarked, "What an exciting milestone for NEXX Systems! This 100<sup>th</sup> system represents the culmination of our efforts to address a broader base of applications, increasing process capability, providing higher throughput and lower cost of ownership. And, we are delighted this customer has chosen to locate an additional Stratus tool at their facility."

Added Tom Walsh, CEO of NEXX: "Today is also a celebration of a banner year for NEXX. NEXX Systems is now a viable company with an installed base of 100 systems offering enabling technology that is key to our customers' success in the advanced packaging market. Meeting our customers' requirements for eutectic and lead-free solder bumps, WLCSP, and 3-D interconnect has permitted NEXX to realize our most successful year in 2009. Kudos to the whole NEXX team, and sincere thanks to all of our customers for the confidence they have shown in selecting NEXX Systems as their partner."

**About Stratus:** Stratus provides industry-leading yield at the lowest cost of ownership for pattern plating and through silicon via (TSV) applications. NEXX Systems has recently introduced AquaTorr™, an advanced prewet system that enables high aspect ratio, void-free copper fill for TSVs. Innovative ShearPlate™ technology provides exception process tuning with exceptional cross wafer uniformity.

**About NEXX:** NEXX Systems brings exceptional technical expertise to the flip chip and advanced packaging markets. Our product lines provide the most efficient, yet affordable, systems of their kind: Nimbus for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: [www.nexxsystems.com](http://www.nexxsystems.com).

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